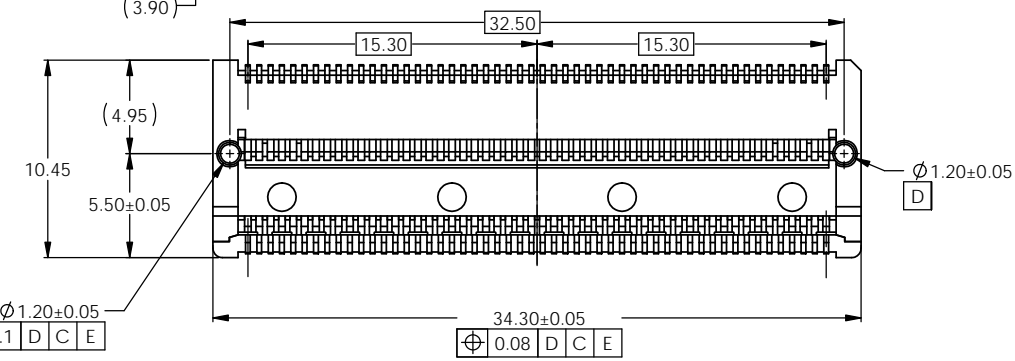
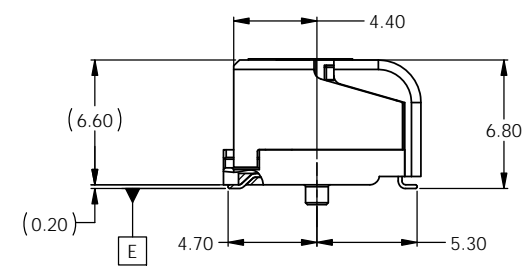
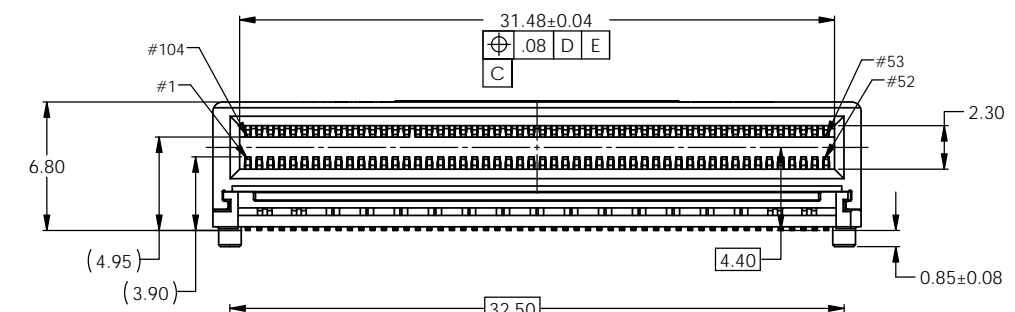
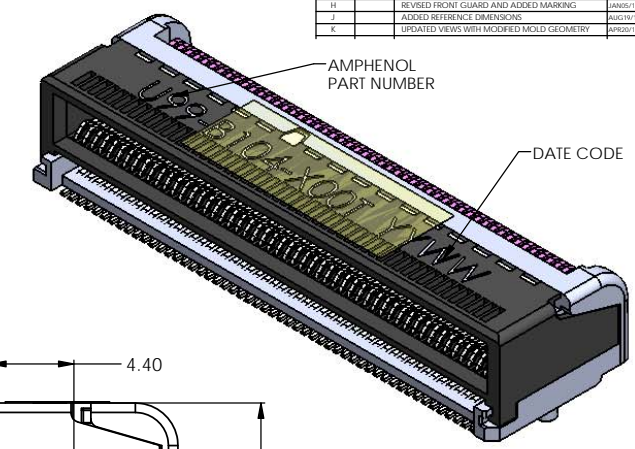
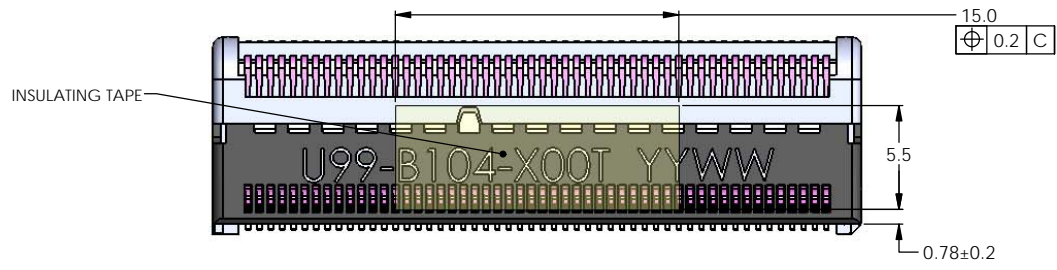
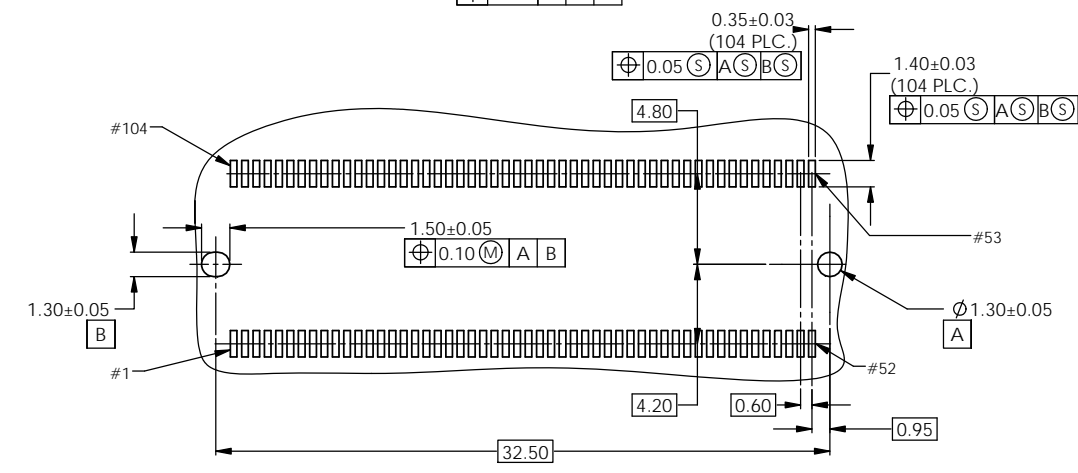


REVISIONS				
REV	ECN	DESCRIPTION	DATE	APPROVED
G		REDRAWN WITH CONTACT HEIGHT REFERENCE ADDED	MAY22/14	CM
H		REVISED FRONT GUARD AND ADDED MARKING	JAN26/15	CM
J		ADDED REFERENCE DIMENSIONS	AUG16/15	CM
K		UPDATED VIEWS WITH MODIFIED MOLD GEOMETRY	APR20/17	CM



U99 - B104 - X X X X

- OPTIONS**
- 00T** = STANDARD CONSTRUCTION WITH TAPE & REEL PACKAGING
 - CONTACT PLATING OPTION**
 - 2** = 30 MICRO INCHES MINIMUM OF GOLD ON MATING END WITH 100 MICRO INCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50 TO 75 MICRO INCHES OF NICKEL UNDER PLATE ALL OVER
 - 3** = 15 MICRO INCHES MINIMUM OF GOLD ON MATING END WITH 100 MICRO INCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50 TO 75 MICRO INCHES OF NICKEL UNDER PLATE ALL OVER



- NOTES:**
- MATERIAL:**
HOUSING: SOLDER REFLOW PROCESS COMPATIBLE LCP, UL94V-0
CONTACTS: PHOSPHOR BRONZE
RESONANCE DAMPENING FEATURE: CONDUCTIVE POLYMER
 - ROHS COMPLIANT**



DO NOT SCALE DRAWING

RECOMMENDED PCB LAYOUT

THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION AND SUCH INFORMATION MAY NOT BE DISCLOSED TO OTHERS FOR ANY PURPOSE OR USED FOR MANUFACTURING PURPOSES WITHOUT PERMISSION FROM AMPHENOL CANADA CORP.

APPROVALS		DATE	Amphenol High Speed Interconnects	
DRAWN	K. LIU	JUN05/12	TITLE	CFP2 4x25G
DESIGNED	C. MICHLIK	JUN05/12	PROJECT	104 POSITION CONNECTOR
CHECKED	ZLJ	JUN05/12	SCALE	NTS
DRAWN			PROJECT	CFP2
DWG. REL. NO.	E. APPD.		DWG. NO.	P-U99-B104-XXXX
CODE IDENT. NO.	03554	DWG. APPD.	C. MICHLIK	JUN05/12
		SCALE	NTS	PROJECT
				SHEET
				1 OF 1